Intel® Server Board SE7500WV2
Memory List Test Report Summary

intel.

Revision History		
Date	**Rev**	**Modifications**
May/02	0.5	Initial post-launch release for review.
June/02	1.0	Release document
July/02	2.0	Added Samsung 256MB, 512MB & 1G parts. Added Netlist 1G part. (In shaded area)
July/02	3.0	Added Infineon 128MB & 512MB parts. Added Micron 128MB part. Added Samsung 256MB part. (In shaded area)
Aug/02	4.0	Added ATP 256MB & 512MB parts. Added Dataram 256MB, 512MB & 1GB parts. Added Ventura 512MB & 1GB parts. Added Hynix 256MB part. Added Samsung 512MB part. (In shaded area)
Aug/02	5.0	Added ATP 128MB, 256MB, & 512MB parts. Added Avant 512MB parts. Added Aved 256MB & 512MB parts. Added Dataram 512MB & 1GB parts. Added Smart 1GB parts. Added Samsung 128MB, 256MB & 512MB parts. (In shaded area)
Sept/02	6.0	Added Smart 128MB & 256MB parts. Added Infineon 256MB & 512MB parts. (In shaded area)
Sept/02	7.0	Added ATP 1GB parts. Added Avant 512MB & 1GB parts. Added Centon 512MB parts. Added Smart Modular 512MB parts. (In shaded area)
Sept/02	8.0	Added Netlist 1G part. (In shaded area)
Oct/02	9.0	Added Avant 1GB parts. Added JITCO 1GB parts. Added ATP 512MB parts. (In shaded area)
Oct/02	10.0	Added Kingston 128MB parts. Correction made to Netlist 1G part, part is actually 512MB part. Added Infineon 256MB part. Added Netlist 512MB part. & Apacer 256MB & 512MB parts. (In shaded area)
Oct/02	11.0	Added Avant 512MB parts. (In shaded area)
Nov/02	12.0	Added Buffalo 256MB & 512MB parts. Added Centon 1GB parts. Added DaneElec 512MB parts. Added Transcend 1GB parts. (In shaded area)
Dec/02	13.0	Added ATP 1GB parts. Added ITUACOM 256MB & 512MB parts. Added Avant & Legend 512MB parts. (In shaded area)
Jan/03	14.0	Added ATP, Legend & Avant 1GB parts. Added ATP and MSC 256MB parts. Added ATP, Dataram, Legend, MSC & Ventura 512MB parts. (In shaded area)
Jan/03	15.0	Added MSC 1GB parts. Added Infineon 256MB parts. Added Viking 256MB parts. Added Buffalo 512MB parts. Added Ventura 512MB parts. (In shaded area)
Jan/03	16.0	Added Dataram 1GB parts. Added Viking 512MB parts. Removed Infineon 256MB part. (In shaded area)
Feb/03	17.0	Added Dataram, Avant, & Transcend 512MB parts. Added Avant, ATP & Micron 1GB parts. (In shaded area)
Mar/03	18.0	Added Virtium 512MB parts. Removed Kingston 128MB part as the part is EOL. (In shaded area)
Mar/03	19.0	Added Viking 256MB & 512MB parts. Added Avant 1GB parts. (In shaded area)
April/03	20.0	Added 512MB and 1GB Avant parts. (In shaded area)
May/03	21.0	Added 512MB Viking parts. Added 1GB Avant parts. (In shaded area)
June/03	22.0	Added Viking 256MB parts. Added Buffalo and Smart 512MB parts. (In shaded area)
June/03	23.0	Added Buffalo 256MB parts. Added Avant And Viking 512MB parts. Added Centon 1GB parts. (In shaded area). Also updated EOL status.
July/03	24.0	Added TRS 512MB parts. Added Viking 1GB parts. (In shaded area)
July/03	25.0	Added TRS 256MB parts. Added Buffalo 1GB parts. (In shaded area)
Aug/03	26.0	Added Centon 256MB parts. (In shaded area). Updated EOL status.
Sept/03	27.0	Added Viking & TRS 1GB parts. (In shaded area)
Oct/03	28.0	Added Centon 512MB & 1GB parts. (In shaded area). Also updated EOL status.
Nov/03	29.5	Added Legend 256MB, 512MB, 1GB. Added Avant 512MB parts. Added TRS 2GB parts. (In shaded area)
Nov/03	30.0	Added Avant 1GB parts. (In shaded area)
Dec/03	31.0	Added Dataram 2GB parts. (In shaded area)
Jan/04	32.0	Added Legend 1GB parts. (In shaded area)
Jan/04	33.0	Updated EOL status.
Feb/04	34.0	Added Dane-Elec 256MB parts. Added TRS 1GB parts. Added Micron 2GB parts. New CMTL address (In shaded area)
Mar/04	35.0	Added TRS 1GB parts. (In shaded area)
Mar/04	36.0	Updated EOL status
Aug/04	37.0	Added Viking 2GB parts. (In shaded area)
Sept/04	38.0	Added Viking 256MB, 512MB and 1GB parts. Added Legend and TRS 512MB parts.(In shaded area)

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The hardware vendor remains solely responsible for the design, sale and functionality of its product, including any liability arising from product infringement or product warranty. Only approved software drivers and accessories that are recommended for the revision number of the boards and system being operated should be used with Intel products. Please note that, as a result of warranty repairs or replacements, alternate software and firmware versions may be required for proper operation of the equipment.

The Intel® Server Board SE7500WV2 may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request.

Please Note: DIMM devices with gold contacts should NOT be placed into DIMM sockets with tin-lead contacts or vice-versa. Mixing dissimilar metal contact types has been shown to result in unreliable memory operation. Intel recommends similar manufacturer and similar speeds in each bank on the memory module. Mixing of dissimilar memory manufacturer and similar speeds in each bank on the memory module is NOT recommended.

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Overview of Memory Testing

The following procedure is used to test memory modules for use in the Intel® Server Board SE7500WV2. Memory is a vital subsystem in a platform. Intel Corporation requires strict guidelines to be met before a memory vendor and part is put onto the qualified memory list. Each Intel Server Board product has a separate qualified memory list.

Memory qualification for Intel's Server Board products is performed by Intel's Memory Validation Laboratory (MVL), and by an independent external test laboratory, Computer Memory Test Lab (CMTL)[1]. CMTL is a leading memory testing organization responsible for testing a broad range of memory products. Memory devices tested by Intel's MVL or CMTL must undergo rigorous tests to ensure that the product will perform the intended server functions.

Intel®'s Server and Workstation Board qualified memory lists categorize memory modules as Advanced Tested. The Advanced Testing process involves a paper qualification, a standard voltage and room temperature functional test, and a voltage and temperature margin functional test. A paper qualification is a review of critical timings, electrical characteristics, timing requirements, environmental requirements, and packaging requirements in order to see if the memory meets Intel's memory specifications. The standard voltage and room temperature test involves testing the memory module on the particular Intel board for which it is being qualified with test software operating under Microsoft* Windows* 2000 Advanced Server for no less than 24 hours. The voltage and temperature margin testing involves testing the memory module on the particular Intel board for which it is being qualified with various test software and operating systems for 48-72 hours under various voltage and temperature margin conditions. Memory modules that have completed Advanced Testing are known to be compatible with the product on which they were tested, and with the test software and operating system that was utilized during the test procedure.

For information regarding the testing procedure required to reach each phase, please contact your Intel Representative.

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[1] CMTL is a leading memory testing organization responsible for testing a broad range of memory products. Receiving a "PASS" after being tested by CMTL, means that a product functions correctly and consumers can use it to perform the intended server functions. In order to pass these stringent standards, memory products must maintain the highest manufacturing procedures and pass an exacting battery of tests. Testing is performed with equipment and a procedure as defined by Intel's various functional testing levels. CMTL contact:

Office: (949) 716-8690	Computer Memory Test Lab (CMTL)
Fax (949) 716-8691	24 Hammond Suite F
	Irvine, CA 92618
	http://www.cmtlabs.com/

Qualified Memory for the Intel® Server Board SE7500WV2

The memory module on the server board SE7500WV2 has 6 DIMM sockets, which can hold up to 12 GB of Registered ECC DDR200 or DDR266 memory using six 72-bit DIMM modules. The following memory features are supported:

- DDR200 and DDR266 registered ECC compatible 2.5V modules (in compliance with the DDR JEDEC DIMM Specification)
- DIMMs with capacity of 128MB, 256 MB, 512 MB, 1G and 2G. Other DRAM sizes may function correctly but will not be validated.
- Minimum configuration is 256MB using two 128MB DIMM.

The memory controller in the E7500 chip set supports memory scrubbing, single-bit error correction and multiple-bit error detection and chip kill support with x4 DIMMs. Memory can be implemented with either single sided (one row) or double-sided (two row) DIMMs. Chipkill Correct Memory architecture gives the memory sub-system the ability to withstand a multibit failure within a DRAM device, including a failure that causes incorrect data on all data bits of the device. The chipset can only support chipkill architecture with DIMMs that are built consisting of x4 DRAM devices.

Below is a chart that lists the current supported memory types: Note:

DDR200 and DDR266 Registered DRAM Module Configurations for Cas Latency 2 & 2.5					
DIMM Capacity	DIMM Organization	DRAM Density	DRAM Organization	# DRAM Devices/rows/Banks	# Address bits rows/Banks/column
128MB	16M x 72	128Mbit	16M x 8	9/1/4	12/2/10
256MB	32M x 72	128Mbit	32M x 4	18/1/4	12/2/11
256MB	32M x 72	128Mbit	16M x 8	18/2/4	12/2/10
256MB	32M x 72	256Mbit	32M x 8	9/1/4	13/2/10
512MB	64M x 72	256Mbit	64M x 4	18/1/4	13/2/11
512MB	64M x 72	256Mbit	32M x 8	18/2/4	13/2/10
512MB	64M x 72	512Mbit	64M x 8	9/1/4	13/2/11
1GB	128M x 72	256Mbit	64M x 4	36/2/4	13/2/11
1GB	128M x 72	512Mbit	64M x 8	18/2/4	13/2/11
1GB	128M x 72	512Mbit	128M x 4	18/1/4	13/2/12
2GB	256M x 72	512Mbit	128M x 4	36/2/4	13/2/12

 Memory features are detailed in *the Intel® Server Board SE7500WV2 Technical Product Specification* available on-line at http://support.intel.com/support/motherboards/server/SE7500WV2

The following table lists DIMM devices known to be compatible with the Intel Server Board SE7500WV2. Intel recommends that Advanced Tested DIMMs be used to establish reliable system operation. DIMM devices not listed can be used; but, in the event of unreliable system operation, the DIMM devices should be replaced with functionally Advanced Tested DIMMs to determine whether the DIMM devices are causing the problem.

Caution: Third party memory vendors may use the same module part number with different DRAM vendors and die revisions. To insure proper system operation, verify that each DRAM vendor and die revision has been separately tested and qualified. Please notify CMTL if there is a discrepancy.

Note: This list is not intended be all-inclusive. It is provided as a convenience to Intel's general customer base, but Intel does not make any representations or warranties whatsoever regarding the quality, reliability, functionality, or compatibility of these memory modules.

This list is subject to change without notice.

Server Board SE7500WV2

Registered, ECC, DDR200 DIMM Modules
128MB Sizes (16Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
Samsung	M312L1713DT0-CA0	K4H280838D-TCA0	Samsung		5/16/02	2	Yes	16Mx8	
Micron	MT9VDDT1672G-202Z1	MT46V16M8-75A	Micron		6/5/02	2		16Mx8	
Samsung	M383L1713CT1-CA0	K4H280838C-TCA0	Samsung		6/13/02	2		16Mx8	

Registered, ECC, DDR266 DIMM Modules
128MB Sizes (16Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
Infineon	HYS72D16500GR-7-A	HYB25D128800AT-7	Infineon		6/9/02	2		16Mx8	
Micron	MT9VDDT1672G-265B2	MT46V16M8-75B	Micron		6/12/02	2.5		16Mx8	
Hynix	HYMD116G725B8M-H	HY5DU28822BT-H	Hynix		6/14/02	2.5		16Mx8	
Micron	MT9VDDT1672G-265B1	MT46V16M8-75B	Micron		7/13/02	2.5		16Mx8	
Infineon	HYS72D16000GR-8-A	HYB25D128800AT-8	Infineon		7/13/02	2		16Mx8	
Samsung	M383L1713DTS-CA2	K4H280838D-TCA2	Samsung		8/10/02	2		16Mx8	
+ATP Electronics	AB16L72A8SEB0S	K4H280838D-TCB0 rev D	Samsung	SB184A08L rev 1	8/16/02	2.5		16Mx8	EOL
+Smart Modular Technologies	SM1672RDDR301-ICA	K4H280838C-TCA2 rev C	Samsung	P51G184NEBZ6IB1 rev A	8/20/02	2		16Mx8	EOL
+Smart Modular Technologies	SM1672RDDR301-ICB	NT5DS16M8AT-7K	Nanya	P51G184NEBZ6IB1 rev A	8/20/02	2		16Mx8	EOL

Modules shaded in blue are low profile

(+) This vendor is part of the CMTL Certification program. This means this part has/will been tested across all compatible Intel Server Boards.   For further information contact CMTL @ http://cmtlabs.com/

Caution: *Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal & physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.*

Server Board SE7500WV2

Registered, ECC, DDR200 DIMM Modules
256MB Sizes (32Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
Infineon	HYS72D32501GR-8-A	HYB25D128400AT-8	Infineon		5/28/02	2	Yes	32Mx4	
Hynix	HYMD132G7258-L	HY5DU28822T-L	Hynix		6/5/02	2		16Mx8	
Samsung	M383L3310CT1-CA0	K4H280438C-TCA0	Samsung		6/27/02	2		32Mx4	
Infineon	HYS72D32000GR-8-A	HYB25D256800BT-8	Infineon		9/11/02	2		32M x 8	

Registered, ECC, DDR266 DIMM Modules
256MB Sizes (32Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
Micron	MT9VDDT3272G-265B2	MT46V32M8-75 B	Micron		6/12/02		Yes	32Mx8	
Micron	MT9VDDT3272G-265B1	MT46V32M8-75 B	Micron		6/15/02			32Mx8	
Samsung	M383L3310DTS-CA2	K4H280438D-TCA2	Samsung		7/13/02			32Mx4	
+Dataram	DTM63640B	MT46V32M4TG-75 rev B	Micron	40581A	8/5/02	2.5	Yes	32M x 4	
Hynix	HYMD132G725B4M-H	HY5DU28422BT-H	Hynix		8/01/02	2.5	Yes	64Mx4	
+ATP Electronics	AB32L72R4S4B0S	K4H280438C-TCB0 rev C	Samsung	SB184R04L1	7/16/02	2.5	Yes	32M x 4	EOL
+ATP Electronics	AB32L72A8S4B0	NT5DS16M8AT-7K rev D	Nanya	SB184A08L rev.1	8/9/02	2.5		16M x 8	EOL
+ATP Electronics	AB32L72A8S4B0S	K4H280838D-TCB0 rev D	Samsung	SB184A08L rev1	8/5/02	2.5		16M x 8	EOL
Samsung	M312L3310DT0-CA2	K4H280438D-TCA2	Samsung		8/10/02	2	Yes	32M x 4	
+Aved Memory Products	AMP383D3313DT1-CA2/S	K4H280838D-TCA2 rev D	Samsung	105601 rev A	8/13/02	2		16M x 8	EOL
Infineon	HYS72D32300GBR-7-B	HYB25D256800BC-7	Infineon		8/24/02	2	Yes	32M x 8	
+Smart Modular Technologies	SM3272RDDR301-ICB	NT5DS16M8AT-7K	Nanya	P51G184NEBZ6IB1 rev A	8/29/02	2		16M x 8	EOL
Apacer	Apacer 75.85380.790	HYB25D256400BT-7	Infineon		10/11/02	2	Yes	64M x 4	
+Buffalo	DD266-R256/SD	K4H280838D-TCB0 rev D	Samsung	RCE0501-AB	11/11/02	2.5		16M x 8	EOL
ITAUCOM	256E2665R28	ICM4L560807-65	Micron	0162 B	11/21/02	2.5		32M x 8	EOL

Registered, ECC, DDR266 DIMM Modules
256MB Sizes (32Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+ATP Electronics	AB32L72Q8SQB0S	K4H560838D-TCB0 rev D	Samsung	SB184Q08L1	12/5/02	2.5	Yes	32M x 8	EOL
+MSC Vertriebs GmbH	MSC 256M00093	HYB25D256800BT-7 rev B	Infineon	PCB M0481LA2	12/17/02	2		32M x 8	EOL
+MSC Vertriebs GmbH	MSC 256M00097	MT46V32M8TG-75 revB	Micron	PCB M0481LA2	12/12/02	2.5		32M x 8	EOL
+Viking	VI4CR327224CTHL1	K4H280438D-TCB0 rev D	Samsung	03-0291 Rev A	1/9/03	2.5	Yes	32M x 4	EOL
+Viking	VI4CR327228DTHL1	K4H560838D-TCB0 rev D	Samsung	0000905A	1/10/03	2.5	Yes	32M x 8	EOL
+Viking	VI4CR327228DTHL2	MT46V32M8TG-75 rev B	Micron	0000905A	3/13/03	2.5	Yes	32M x 8	EOL
+Viking	VI4CR327228DTHL3	MT46V32M8TG-75 rev C	Micron	0000905A	5/9/03	2.5	Yes	32M x 8	
+Buffalo	DD266L-RS256/SD	K4H560838D-TCB0 rev D	Samsung	1D188EF-AA	5/26/03	2.5	Yes	32M x 8	
+TRS	TRS21150	HYB25D256800BT-7 rev B	Infineon	M0529LA1 rev 1	6/27/03	2	Yes	32M x 8	
+Centon Electronics	TOP02-D004D	MT46V32M4TG-75 rev B	Micron	LE36DDT1844R rev A	7/30/03	2.5	Yes	32M x 4	EOL
+Legend	L3272YC5-RU1HDC5B	HY5DU56822BT-J rev B	Hyundai	DRR1U0818-A rev 1	10/30/03	2.5	Yes	32M x 8	
+Dane-Elec	ODLD266R072325I-1MC	MT46V32M8TG-6T rev C	Micron	DR1G872-A rev A	2/5/04	2.5	Yes	32M x 8	
+Viking	VI4CR327228DTHL4	MT46V32M8TG(P)-6T rev G	Micron	0000985A	8/2/04	2.5	Yes	32M x 8	

Modules shaded in blue are low profile

(+) This vendor is part of the CMTL Certification program. This means this part has/will been tested across all compatible Intel Server Boards.   For further information contact CMTL @ http://cmtlabs.com/

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Server Board SE7500WV2								
Registered, ECC, DDR200 DIMM Modules **512 MB Sizes (64Mx72)**								
Manufacturer	**Part Number**	**DRAM Part Number**	**DRAM Vendor**	**PCB Part Number**	**Date**	**CAS Latency**	**Low Profile**	**DRAM Organization**	**EOL**
Infineon	HYS72D64000GR-8-A	HYB25D256400AT-8	Infineon		5/22/02	2		64Mx4	
Samsung	M383L6420DTS-CA0	K4H560438D-TCA0	Samsung		7/5/02	2		64Mx4	
Samsung	M312L6420DT0-CA0	K4H560438D-TCA0	Samsung		7/26/02	2		64Mx4	
Registered, ECC, DDR266 DIMM Modules **512 MB Sizes (64Mx72)**								
Manufacturer	**Part Number**	**DRAM Part Number**	**DRAM Vendor**	**PCB Part Number**	**Date**	**CAS Latency**	**Low Profile**	**DRAM Organization**	**EOL**
Micron	MT18VDDT6472G-265B2	MT46V64M4-75 B	Micron		6/18/02	2.5	Yes	64Mx4	
Infineon	HYS72D64500GR-7-A	HYB25D256400AT-7	Infineon		7/16/02	2	Yes	64Mx4	
+ATP Electronics	AB64L72R4S8B0S	K4H560438D-TCB0 rev D	Samsung	SB184R04L1	7/29/02	2.5	Yes	64M x 4	EOL
+Dataram	DTM63641A	HYB25D256400AT-7 rev A	Infineon	40581AA	7/25/02	2.5	Yes	64M x 4	EOL
Ventura Technology Group	D52WVK25SV	K4H560838C-TCB0 rev C	Samsung	V208	7/23/02	2.5		32M x 8	EOL
+ATP Electronics	AB64L72A8S8B0S	K4H560838D-TCB0 rev D	Samsung	SB184A08L	8/7/02	2.5		32M x 8	EOL
+Avant Technology	AVM7264R38C5266K0-A	K4H560438C-TCB0 rev C	Samsung	50-1415-01 rev B	8/15/02	2.5	Yes	64M x 4	EOL
+Aved Memory Products	AMP383D6420CT3-CB0/S	K4H560438C-TCB0 rev C	Samsung	105611 rev A	8/13/02	2.5	Yes	64M x 4	EOL
+Dataram	DTM63641B	MT46V64M4TG-75 rev B	Micron	40581A	8/7/02	2.5	Yes	64M x 4	EOL
Samsung	M383L6420DTS-CA2	K4H560438D-TCA2	Samsung		8/21/02	2		64M x 4	
Infineon	HYS72D64320GBR-7-B	HYB25D256800BC-7	Infineon		8/24/02	2	Yes	32 x 8	
+Avant Technology	AVM7264R39C2266K1-A	NT5DS32M8AT-7K rev A	Nanya	50-1411-01-A rev A	9/10/02	2	Yes	32M x 8	EOL
+Centon Electronics	CMB512M/RD266S	MT46V32M8TG-75 rev B	Micron	DR513872 rev A	9/13/02	2.5		32M x 8	EOL
+Smart Modular Technologies	SM6472RDDR301B-ICA	K4H560438D-TCA2	Samsung	P512184NVSZ6GAX rev A	9/3/02	2		64M x 4	EOL
+ATP Electronics	AB64L72A8S8B0	NT5DS32M8AT rev D	Nanya	SB184A08L rev1	9/19/02	2.5		32M x 8	EOL
Netlist	NL9647RD64042-D21J	K4H560438D-TCB0	Samsung		09/10/02	2.5	Yes	64M x 4	
Apacer	Apacer-75.96280.791	HYB25D256400BT-7	Infineon		10/11/02	2	Yes	64M x 4	

Registered, ECC, DDR266 DIMM Modules 512 MB Sizes (64Mx72)									
Manufacturer	**Part Number**	**DRAM Part Number**	**DRAM Vendor**	**PCB Part Number**	**Date**	**CAS Latency**	**Low Profile**	**DRAM Organization**	**EOL**
+Avant Technology	AVM7264R39C5266K1-A	K4H560838C-TCB0 rev C	Samsung	50-1411-01-A rev A	10/17/02	2.5	Yes	32M x 8	EOL
+Buffalo	DD266-R512/MB	46V32M8-75 rev B	Micron	RCE0501-AB	11/8/02	2.5		32M x 8	EOL
+Dane-Elec	D1D266R072642I	NT5DS32M8AT-7K rev A	Nanya	DR513872 rev A	11/1/02	2		32M x 8	EOL
+Dane-Elec	D1D266R072642H	HYB25D256400AT-7 rev A	Infineon	DE042036 rev B	10/29/02	2	Yes	64M x 4	EOL
+Avant Technology	AVM7264R38C2266K0-A	NT5DS64M4AT-7K rev A	Nanya	50-1415-01 rev B	11/22/02	2	Yes	64M x 4	EOL
ITAUCOM	512E2665R24	ICM4L560407-65	Micron	0163 A	12/2/02	2.5		64M x 4	EOL
+Legend	L6472TC5-RR2HDC5A	HY5DU56822AT-H rev A	Hyundai	DRR720818A rev 2	11/26/02	2.5		32M x 8	EOL
+ATP Electronics	AB64L72Q8S8B0S	K4H560838D-TCB0 rev D	Samsung	SB184Q08L1 rev 1	12/4/02	2.5	Yes	32M x 8	EOL
+Legend	L6472YC5-PPASDC5D	K4H560438D-TCB0 rev D	Samsung	18-25141A rev A	12/4/02	2.5	Yes	64M x 4	EOL
+MSC Vertriebs GmbH	MSC 512M00094	HYB25D256800BT-7 rev B	Infineon	PCB M0481LA2	12/11/02	2		32M x 8	EOL
+MSC Vertriebs GmbH	MSC 512M00098	MT46V32M8TG-75 rev B	Micron	PCB M0481LA2	12/11/02	2.5		32M x 8	EOL
Ventura Technology Group	D52WPK31SV	K4H560438D-TCB0 rev D	Samsung	V218	12/19/02	2.5	Yes	64M x 4	EOL
+Dataram	DTM63641E	HYB25D256400BT-7 rev B	Infineon	40581A rev A	12/20/02	2.5	Yes	64M x 4	EOL
+Buffalo	DD266-R512/SD	K4H560838D-TCB0 rev D	Samsung	RCE0501-AB	12/30/02	2.5		32M x 8	EOL
Ventura Technology Group	D52WVK25SVD (Old Part# D52WVK25SV)	K4H560838D-TCB0 rev D	Samsung	V208	1/2/03	2.5		32M x 8	EOL
+Viking	VI4CR647224DTHL1	K4H560438D-TCB0 rev D	Samsung	03-0291 rev A	1/29/03	2.5	Yes	64M x 4	EOL
+Dataram	DTM63641G	MT46V64M4TG-75 rev C	Micron	40581A rev A	2/3/03	2.5	Yes	64M x 4	
+Avant Technology	AVM7264R38C5266K0-A	MT46V64M4TG-75 B rev B	Micron	50-1415-01 rev B	2/7/03	2.5	Yes	64M x 4	EOL
Transcend Information, Inc	TS64MDR72V6F5	V58C2256804SAT7	Mosel - Vitalic	09-1590	2/18/03	2.5	Yes	32M x 8	EOL
Virtium Technology Inc	VM383L6420E-B0	K4H560438D-TCB0 rev D	Samsung	18-25141A rev A	2/28/03	2.5	Yes	64M x 4	EOL
+Viking	VI4CR647228DTHL2	K4H560838D-TCB0	Samsung	0000905A	3/20/03	2.5	Yes	32M x 8	EOL

Registered, ECC, DDR266 DIMM Modules
512 MB Sizes (64Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Avant Technology	AVM7264R38C5266K0-A	MT46V64M4TG-75 C rev C	Micron	50-1415-01-B rev B	4/1/03	2.5	Yes	64M x 4	EOL
Viking	VI4CR647224DTHL2	MT46V64M4TG-75 rev B	Micron	03-0291 rev A	4/7/03	2.5	Yes	64M x 4	EOL
+Buffalo	DD266L-R512/SD	K4H560838D-TCB0 rev D	Samsung	1D188EF-AA	5/19/03	2.5	Yes	32M x 8	EOL
+Smart Modular Technologies	SM6472RDDR3H1LP-M	MT46V64M4TG-75C	Micron	P52G184NESZ6G001 rev A	4/29/03	2.5	Yes	64M x 4	
+Avant Technology	AVM7264R39C5266K1-A	MT46V32M8-75 B rev B	Micron	50-1411-01-A rev A	6/4/03	2.5	Yes	32M x 8	EOL
+Viking	VI4CR647228DTHL4	MT46V32M8TG-75 rev C	Micron	0000905A rev A	5/22/03	2.5	Yes	32M x 8	
+TRS	TRS21151	HYB25D256400BT-7 rev B	Infineon	M0530LA1 rev 1	6/23/03	2	Yes	64M x 4	
+TRS	TRS21152	HYB25D256800BT-7 rev B	Infineon	M0529LA1 rev 1	6/18/03	2	Yes	32M x 8	
+Centon Electronics	TOP02-D019S	MT46V32M8TG-6 rev C	Micron	DR1G872-A	9/26/03	2.5	Yes	32M x 8	
+Legend	L6472YC5-RU1HDC5B	HY5DU56822BT-J rev B	Hyundai	DRR1U0818-A rev 1	11/5/03	2.5	Yes	32M x 8	
+Avant Technology	AVM7264R38C5266K0-A	NT5DS64M4BT-75B rev B	Nanya	50-1415-01-B rev B	10/17/03	2.5	Yes	64M x 4	
+Legend	L6472YC5-182HDD5A	HY5DU56422AT-K rev A	Hyundai	184RL rev 2	10/14/03	2.5	Yes	64M x 4	
+Legend	L6472YC5-PPASDD5D	K4H560438D-TCB3 rev D	Samsung	18-25141A Rev A	8/9/04	2.5	Yes	64M x 4	
+TRS	TRS21202	HYB25D256400CE-7 rev C	Infineon	M0530LA1 rev 1	8/6/04	2	Yes	64M x 4	
+Viking	VI4CR647228DTHL5	MT46V32M8TG(P)-6T rev G	Micron	0000985A	7/27/04	2.5	Yes	32M x 8	

Modules shaded in blue are low profile

(+) This vendor is part of the CMTL Certification program. This means this part has/will been tested across all compatible Intel Server Boards.   For further information contact CMTL @ http://cmtlabs.com/

(~) This part has been found compatible with this product and meets the JEDEC spec for electrical requirements but is 2.05" high, which is above the mechanical specifications.

Caution: *Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal & physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.*

Server Board SE7500WV2
Registered, ECC, DDR200 DIMM Modules
1G Sizes (128Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
Samsung	M312L2828DT0-CA0	K4H560438D-TCA0	Samsung		7/2/02	2	Yes	64Mx4	

Registered, ECC, DDR266 DIMM Modules
1G Sizes (128Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CMTL Test #	CAS Latency	Low Profile	DRAM Organization	EOL
Samsung	M312L2828DT0-CA2	K4H560438D-TCA2	Samsung			6/17/02	2	Yes	64Mx4	
Netlist	NL9127RD64052-D21J	K4H560438D-TCB0	Samsung			6/27/02	2.5	Yes	64Mx4	
+Dataram	DTM63621D	MT46V64M4TG-75 rev B	Micron	40556 rev B		7/31/02	2.5	Yes	64M x 4	EOL
Ventura Technology Group	D54WPK28SV	K4H560438D-TCB0 rev D	Samsung	V213		7/26/02	2.5		64M x 4	EOL
+Dataram	DTM63621C	HYB25D256400AT-7 rev A	Infineon	40556 rev B		8/16/02	2.5	Yes	64M x 4	EOL
+Smart Modular Technologies	SM12872RDDR301-ICB	K4H560438C-TCA2	Samsung	P52G184NVSZKGOX rev A		8/9/02	2		128M x 4	EOL
Netlist	~NL9127RD64042-D21J	K4H560438C-TCB0	Samsung			8/16/02	2		64M x 4	
+ATP Electronics	AB28L72P4SMB0S	K4H560438D-TCB0 rev D	Samsung	SB184P04L1		9/9/02	2.5	Yes	64M x 4	EOL
+Avant Technology	AVM7228R82C2266K1-A	NT5DS64M4AT-7K rev A	Nanya	50-1416-01-A rev A		9/16/02	2	Yes	64M x 4	EOL
JITCO CO LTD	JDDR1GR	HY5DU56422T-H	Hyundai	JDDR2GR		9/27/02	2.5	Yes	128M x 4	EOL
+Centon Electronics	TOP02-C002B (Old Part# CMB1G/RD266S)	MT46V64M4TG-75 rev B	Micron	LE36DDT1844R rev A		10/29/02	2.5	Yes	128M x 4	EOL
+Dataram	DTM63621F	HYB25D256400BT-7 rev B	Infineon	40556 rev B		11/13/02	2	Yes	64M x 4	
Transcend Information, Inc	TS128MDR72V6L5	K4H560438D-TCB0 rev D	Samsung	09-1380		11/4/02	2.5	Yes	64M x 4	EOL
+ATP Electronics	AB28L72T4SQB0S	K4H560438D-TCB0 rev D	Samsung	SB184T04L2 rev 2		11/14/02	2.5		64M x 4	EOL
+ATP Electronics	AB28L72P4SMB0A	NT5DS64M4AT-7K	Nanya	SB184P04L1 rev 1		12/17/02	2.5	Yes	64M x 4	EOL
+Avant Technology	AVM7228R38C2266K3-A	NT5DS64M4AT-7K rev A	Nanya	BRDB45A		12/17/02	2		64M x 4	EOL
+Legend	L1272YC5-PPBSDD5D	K4H560438D-TCB0 rev D	Samsung	18-21040B rev B		12/20/02	2.5	Yes	64M x 4	EOL
+MSC Vertriebs GmbH	MSC001G00096	HYB25D512800AT-7 rev A	Infineon	M0481LA2		12/30/02	2		64M x 8	EOL
+Dataram	DTM63653B	HYB25D256400BC-7 rev B	Infineon	40599A rev A		1/21/03	2.5	Yes	64M x 4	EOL

Registered, ECC, DDR266 DIMM Modules 1G Sizes (128Mx72)									
Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Dataram	DTM63621H	MT46V64M4TG-75 rev C	Micron	40556 rev B	1/23/03	2.5	Yes	64M x 4	EOL
+Dataram	DTM63653C	K4H560438D-GCA2 rev D	Samsung	40599A rev A	1/15/03	2.5	Yes	64M x 4	EOL
+Avant Technology	AVM7228R38C5266K3-A	MT46V64M4TG-75 B rev B	Micron	BRDB45A rev A	1/31/03	2.5		64M x 4	EOL
+ATP Electronics	AB28L72P4SUB0S	K4H560438D-TCB0 rev D	Samsung	SB184P04L1	2/12/03	2.5	Yes	64M x 4	EOL
+Micron	MT36VDDT12872G-265C2	MT46V64M4TG-75 rev C	Micron	0232 rev A	2/20/03	2	Yes	64M x 4	EOL
+Avant Technology	AVM7228R38C5266K3-A	K4H560438D-TCB0 rev D	Samsung	BRDB45A rev A	3/12/03	2.5		64M x 4	EOL
+Avant Technology	AVM7228R82C5266K1-A	MT46V64M4TG-75 B rev B	Micron	50-1416-01-A rev A	3/26/03	2.5	Yes	64M x 4	EOL
+Avant Technology	AVM7228R38C5266K3-A	MT46V64M4TG-75 C rev C	Micron	BRDB45A rev A	4/21/03	2.5		64M x 4	EOL
+Centon Electronics	TOP02-D006F	MT46V64M4TG-75C rev C	Micron	LE36DDT1844R rev A	5/30/03	2.5	Yes	64M x 4	EOL
+Viking	VI4CR287224DYHL2	MT46V64M4TG-75 rev B	Micron	03-0291 rev A	6/11/03	2.5	Yes	64M x 4	EOL
+Buffalo	DD266L-RW1G/SD	K4H560438D-TCB0 rev D	Samsung	4D248EF-AA	7/1/03	2	Yes	64M x 4	
+Viking	VI4CR287224DYHL3	MT46V64M4TG-75 rev C	Micron	03-0291 rev A	8/15/03	2.5	Yes	64M x 4	
+TRS	TRS21153	HYB25D256400BT-7 rev B	Infineon	M0531LA1 rev 1	8/20/03	2	Yes	64M x 4	
+Centon Electronics	TOP02-D023W	HYB25D256400BT-7 rev B	Infineon	LE36DDT1844R rev A	9/15/03	2.5	Yes	64M x 4	
+Legend	L1272YC5-183HDD5A	HY5DU56422AS-H rev A	Hyundai	184RL rev 3	10/24/03	2.5	Yes	64M x 4	
+Avant Technology	AVM7228R82C5266K1-A	NT5DS64M4BT-75B rev B	Nanya	50-1416-01-A rev A	11/13/03	2.5	Yes	64M x 4	
+Legend	L1272YC5-RU1HDH5A	HY5DU12822AT-H rev A	Hyundai	DRR1U0818-A rev 1	12/16/03	2.5	Yes	64M x 8	
+TRS	TRS21174	HYB25D512800AT-7 rev A	Infineon	M0529LA1 rev 1	2/12/04	2	Yes	64M x 8	
+TRS	TRS21171	HYB25D256400BC-7 rev B	Infineon	M0533LA1 rev 1	2/20/04	2	Yes	64M x 4	
+Viking	VI4CR287228ETHL1	MT46V64M8TG(P)-75 rev D	Micron	0000985A	7/29/04	2.5	Yes	64M x 8	

Modules shaded in blue are low profile

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Server Board SE7500WV2
Registered, ECC, DDR200 DIMM Modules
2G Sizes (256Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL

Registered, ECC, DDR266 DIMM Modules
2G Sizes (256Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+TRS	TRS21155	HYB25D512400AT-7 rev A	Infineon	M0531LA1 rev 1	10/22/03	2	Yes	128M x 4	
+Dataram	DTM63663B	HYB25D512400AT-7 rev A	Infineon	40556 rev B	12/02/03	2	Yes	128M x 4	
Micron	MT36VDDF25672G-265C2	MT46V128M4FN-75	Micron	0328 rev A	2/17/04	2.5	Yes	128M x 4	
+Viking	VI4CR567224EYHL3	K4H510438B-TCB3 rev B	Samsung	03-0307 rev B	7/19/04	2.5	Yes	128M x 4	

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When 2GB DIMM's are used with the Intel® Server Board SE7500WV2 integrated into the Intel Server Chassis SR1300 & SR2300, Intel's thermal testing results show that operating these server system configurations at an ambient inlet temperature of 35 degrees Celsius may potentially cause internal system components to exceed their maximum specified operating temperatures. Intel has verified that internal system components do not exceed their maximum specified operating temperatures when the Intel Server Chassis SR1300 server system configurations are operated at a maximum ambient inlet temperature of 30 degrees C. Intel has also verified that internal system components do not exceed their maximum specified operating temperatures when the Intel Server Chassis SR2300 server system configurations are operated using the "Optional Memory Cooling Enhancement Fan Accessory, Product Code: FSWMEMFAN, MM#: 852787" available from Intel. For additional information see TA656-1.

Sales Information

Vendor Name	Web URL	Vendor Direct Sales Info
ATP Electronics	http://www.atpusa.com/	Florence Hsieh Tel 408-732-5831 Fax 408-732-5055 sales@atpusa.com
ATP Electronics -- Taiwan Inc.	http://www.atpusa.com/	Patty Kuo Tel 011-886-2-2659-6368 Fax 886-2-2659-4982
Avant Technology	http://www.avanttechnology.com	Brad Scoggins Phone: (512)491-7411 Fax: (512)491-7412 brads@avanttechnology.com
Aved Memory Products	http://www.avedmemory.com/	
Buffalo Technology	http://www.buffalotech.com/	(800) 967-0959 memory@buffalotech.com
Centon Electronics	http://www.centon.com	Tel: 949-855-9111 Fax: 949-855-6035
Corsair	http://www.corsairmicro.com/	Tel: 510-657-8747 Fax: 510-657-8748
Dane-Elec	http://www.dane-memory.com/	Michal Hassan @ (949)450-2941 or email @ Michal@Dane-memory.com
Dataram	http://www.dataram.com/	Robert Olszak @ 800-822-0071 ext. 2404
GoldenRAM	http://www.goldenram.com	Jason M. Barrette @ 800-222-861 x7546 jasonb@goldenram.com or Michael E. Meyer @800-222-8861 x7512 michaelm@goldenram.com
Hitachi	http://semiconductor.hitachi.com/pointer/	
Hyundai/Hynix Semiconductor	http://www.hea.com/	
Infineon	http://www.infineon.com/business/distribut/index.htm	
ITAUCOM	http://www.itaucom.com.br	
JITCO CO LTD	http://www.jitco.net/	Seong Jeon Tel: 82-32-817-9740 s.jeon@jitco.net
Kingston	http://www.kingston.com	US.- Call (877) 435-8726 Asia – Call 886-3-564-1539 Europe – Call +44-1932-755205
Legacy Electronics Inc.	http://www.legacyelectronics.com	U.S. Contact: Keri Albers 888 466 3853 ext. 307 European Contact: 49 89 370 664 11
Legend	http://www.legend.com.au	
Micron	http://silicon.micron.com/mktg/"http://silicon.micron.com/mktg/mbqual/qual_data.cfm	
MSC Vertriebs GmbH	http://www.msc-ge.com	William Perrigo 49-7249-910-417 Fax: 49-7249-910-229 wpe@msc-ge.com

Vendor Name	Web URL	Vendor Direct Sales Info
Netlist, Inc	http://www.netlistinc.com	Christopher Lopes 949.435.0025 tel 949.435.0031 fax sales@netlistinc.com
Peripheral Enhancements	http://www.peripheral.com/	
PNY	http://www.pny.com/internet_explorer/LPB.HTML	
Samsung	http://www.korea.samsungsemi.com/locate/buy/list_na.html	For US customers go to: http://www.mymemorystore.com/
Silicon Tech	http://www.silicontech.com/contact/salescontacts.shtml	
Simple Tech	http://www.simpletech.com	Ron Darwish @ (949) 260-8230 or email @ Rdarwish@Simpletech.com
SMART Modular Technologies	http://www.smartm.com/channel	Gene Patino (949) 439-6167 Gene.Patino@Smartm.com
Swissbit	http://www.swissbit.com	Tony Cerreta Tel: 914-935-1400 x240 Fax: 914-935-9865 tony.cerreta@swissbitna.com
TechnoLinc Corporation	http://www.technolinc.com	David Curtis 510-445-7400 davidc@technolinc.com
TRS* Tele-Radio-Space GmbH	http://www.certified-memory.com http://www.certified-memory.de	Vendor Direct Sales Info: Andreas Gründl, Pho.: +49(0)89/94553234, Fax.: +49(0)89/94553293, agruendl@trs-space.de
Unigen	http://www.unigen.com	
Ventura Technology Inc	http://www.venturatech.com	Don Hummel @ 805-581-0800 x 108 or email @ don@venturatech.com
Viking InterWorks	http://www.vikinginterworks.com	
Virtium Technology Inc	http://www.virtium.com	Tod Skelton @ (949) 460-0020 ext. 146 or email @ tod.skelton@virtium.com
Legend	http://www.legend.com.au	Tel: 800-338-2361 Fax: 949-459-8577 orderdesk@vikingcomponents.com
Wintec Industries	http://www.wintecindustries.com	Tel 510-360-6300 Fax 510-770-9338

CMTL* (Computer Memory Test Labs)

CMTL is a privately owned and operated memory testing organization responsible for testing a broad range of memory products. Memory devices tested by CMTL must undergo a rigorous battery of tests to ensure that the product will perform the intended server functions. Memory capability is a major factor your customers consider. CMTL has the ability to test and certify memory on Intel-based server platforms. The list of memory modules, which have undergone testing through the CMTL facility, should be referenced when considering modules for integration into this Intel server product. Stringent standards with regard to manufacturing procedures and quality must be met to pass the exacting tests required for qualification through the independent testing facility. Testing is performed by CMTL with Intel server products and test procedures defined by Intel's Memory Validation Lab. Intel routinely audits the CMTL facility to ensure all procedures, process handling, and testing methodologies are met.